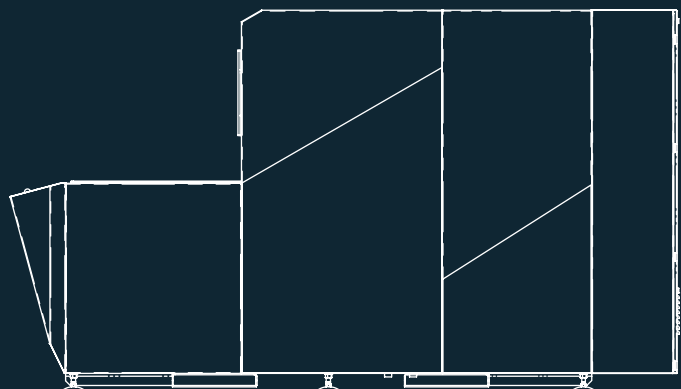
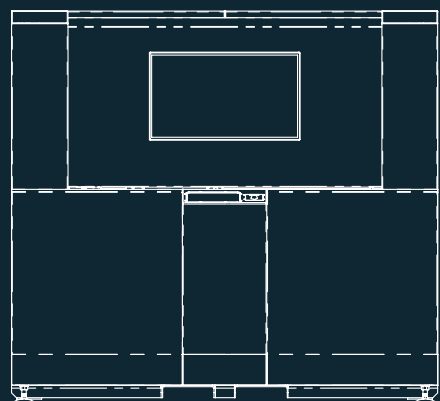
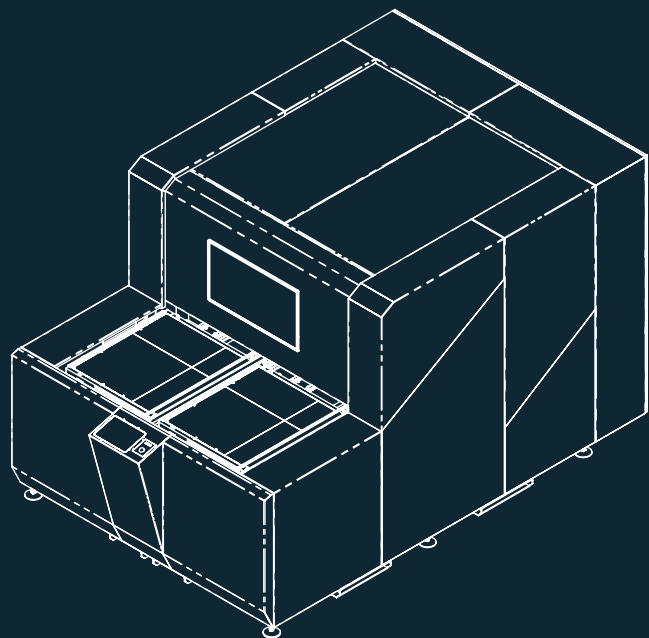


Inner-Layer  
Outer-Layer  
Soldermask  
(PSR)

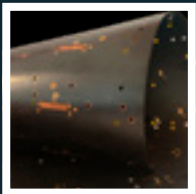


Processes	Inner Layer, Outer Layer & Soldermask		
Exposure Area	From 228mm x 254mm (9"x10") up to 610mm x 762mm (24"x30")		
Panel Thickness	0.05mm to 8mm - 6kg max.		
Light Configuration	Separate Photoheads		BeamLight™
Light Engine	LS15	LS30	Multichannel
Resolution - L/S	15µm/15µm (0.6/0.6 mil) <sup>(1)</sup>	30µm/30µm (1.2/1.2 mil) <sup>(1)</sup>	30µm/30µm (1.2/1.2 mil) <sup>(1)</sup>
Resolution – DAM	25µm (1 mil) <sup>(1)</sup>	50µm (2 mils) <sup>(1)</sup>	50µm (2 mils) <sup>(1)</sup>
Resist Capability	From 10 to 2,000 mJ/cm² and above		
Wavelength	4 UV LED per Head/Channel : 365nm to 405nm		
Alignment	± 12µm Side to Side Alignment ± 8µm Image to Panel (holes or pads) <sup>(2)</sup>		
CCD Cameras	Image Alignment: Movable Cameras I «On the fly» Detection Process Image DMD Calibration		
Productivity	Adix SA duo with BeamLight™ 610x457mm @30mJ - 277 Sides/hour <sup>(3)</sup>		
Dimensions (mm) & Weight	2,900 (L) x 2,100 (W) x 1,900 (H) - 4.5T		
Automation	Altix PT/F - Pass Through / Flip Solution (optional)		

(1) Depending on Photoresist, Surface Preparation and DES process  
(2) With max deformation of the panel for tightest registration is ±0.004%  
(3) Estimated time given as reference but can fluctuate according to the process adjustments



PCB



FPCB /FLEX



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MILLING



ADVANCED  
PACKAGING

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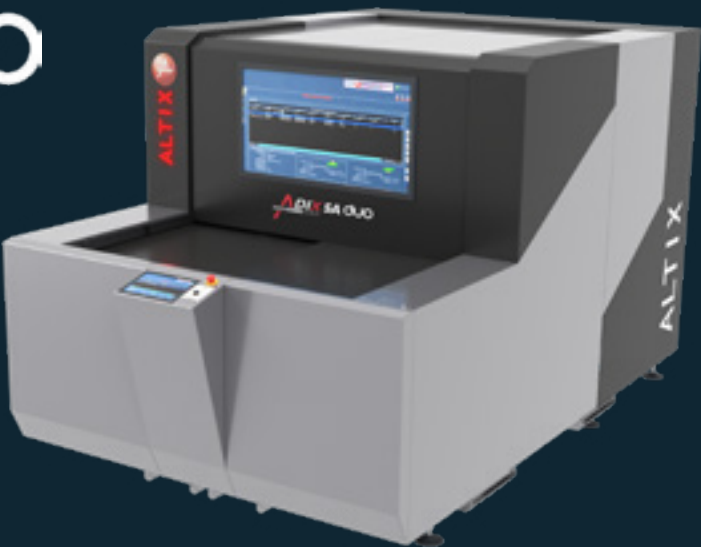
· Manufacturing, Sales & Service: Europe  
Altix France – HQ  
Email: [sales@altix.fr](mailto:sales@altix.fr)

· Direct Sales & Service: Asia  
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Shanghai, Kunshan, Zhuhai Offices  
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Altix North America, Inc.  
West Coast, Mid West and East Coast  
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Direct Imaging



## Enhanced Ergonomy



Main HMI Display



Trackball



Touch Screen

Following extensive user experience case studies, the final design allows for maximum operator comfort while staying true to the Adix range's optimized footprint.

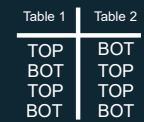
## Dual Table



Twin Stage



Large Panel Exposure

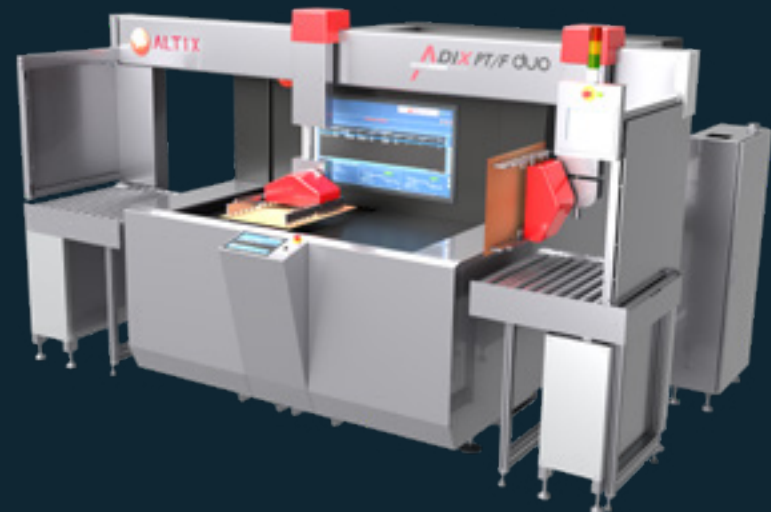


Adaptive Exposure Modes



Not only do the two trays work simultaneously, the light sources are in operation during 90% of the total production cycle. The optimization is in part thanks to Altix's advanced lighting & vision systems detecting fiducials on-the-fly.

## Pass Through / Flip Automation



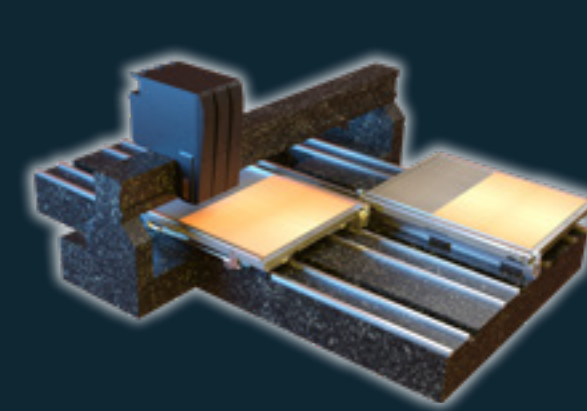
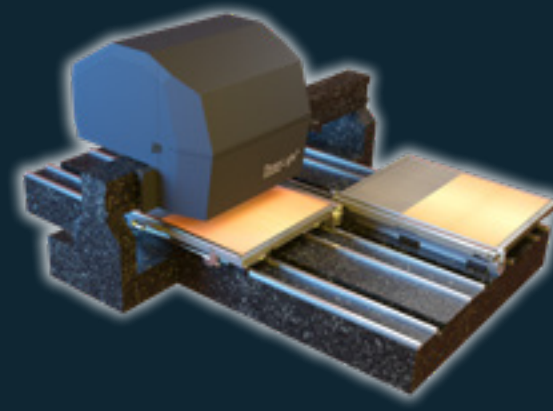
In the Air Flip



Dry Film & Soldermask Compatible

The Adix SA duo can be coupled to our PT/F automation module in order to integrate the equipment in a fully automatic line.

## Available DMD/LED Light Sources



### BeamLight™

A creative combination of 4 high-density LED light sources through a unique optical device coupled to a high frequency (up to 20kHz) DMD.

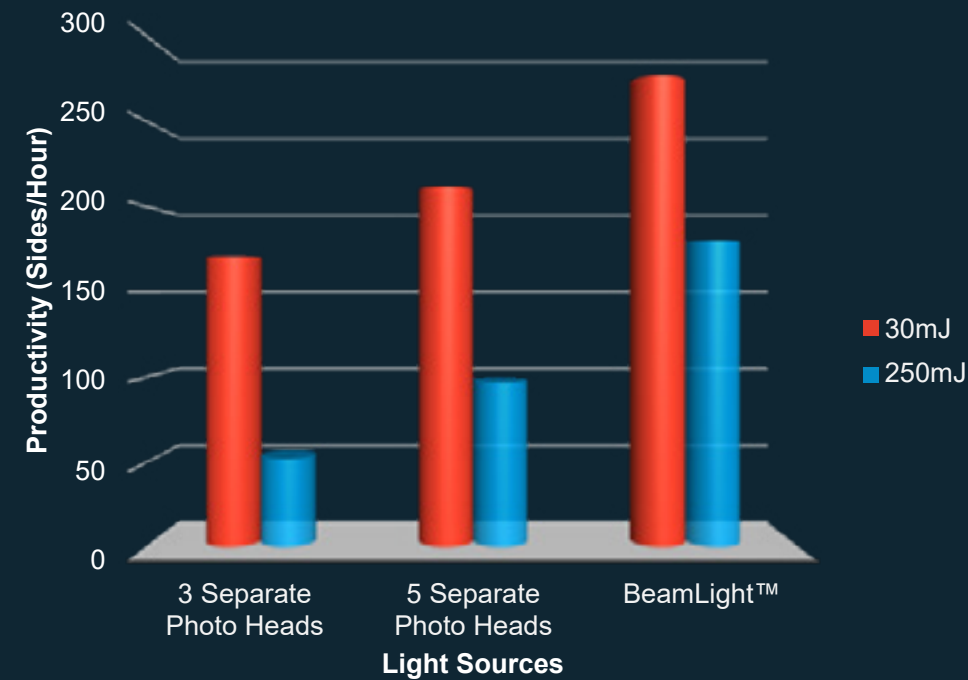
The BeamLight™, has a minimum L&S of 30µm.

### Photoheads

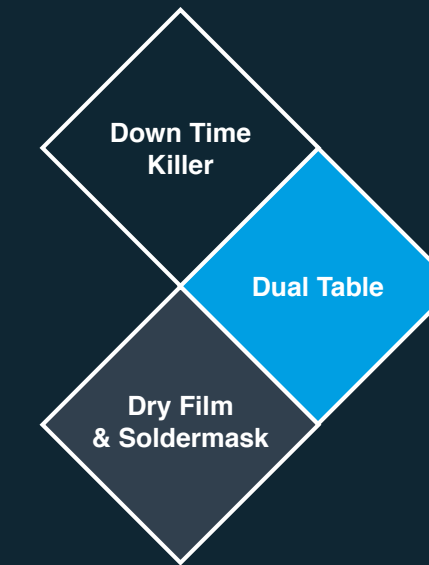
As an alternative to BeamLight™, the number of separate photoheads are chosen according to your productivity and resolution requirements.

Configurations range from 2 to 7 photoheads with a minimum L&S capability of 15µm.

## High Throughput



Scan for the Product Showcase Video:



## Human Machine Interface (HMI)

Ensuring a smooth user experience, a 43" main screen coupled to a 10" touch screen for vision control enables efficient job setup, parameter monitoring, full diagnosis as well as process optimization. The ALTIX Direct Imaging Suite™ software offers a multilingual operating system.

## Multi Wavelength UV-LEDs

With 4 LED wavelengths (365/380/395/405nm) and by adjusting the output ratio, a wide range of dry films, ink & solder resists can be effectively polymerized.

UV-LEDs consume less energy, generate less heat, and last much longer than typical laser diode or blue laser-based light sources.

## Smart Vacuum & Clamping Technology

Vacuum and clamping adjust automatically according to panel size.

The clamping system can safely hold warped PCBs and handle panel thickness from 40µm to 6mm.

## High Dynamic Autofocus Function

A precise and dynamic autofocus system is integrated inside each channel. Real-time feedback allows the detection and correction of board warping and surface thickness variations at ±4mm. This contributes to consistent imaging and drastically reduces imaging errors.

## High Accuracy Registration

The vision system consisting of multiple high resolution CCD cameras enables alignment via through holes, copper pads or various alignment marks.

Registering targets on-the-fly erases downtime: 90% of the cycle is pure imaging. Image-to-panel registration goes down to ±8µm for high-end HDI designs.

Side-to-side registration for inner layers enables high accuracy alignment down to ±12µm thanks to our exceptional registration system with adjustable points fitted in accordance with panel size.



Quality Assurance Program

